



Material Content Data Sheet



Sales Product Name				IFX25001TF V50		Issued		26. September 2017	
MA#				MA000714756					
Package				PG-TO252-3-11		Weight*		379.69 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.179	0.84	0.84	8372	8372	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		567		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		170		
	non noble metal	copper	7440-50-8	215.017	56.62	56.70	566293	567030	
wire	non noble metal	aluminium	7429-90-5	0.141	0.04	0.04	372	372	
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		702		
	plastics	epoxy resin	-	12.261	3.23		32293		
	inorganic material	silicondioxide	60676-86-0	120.747	31.80	35.10	318014	351009	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9850	9850	
plating	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
solder	noble metal	silver	7440-22-4	0.119	0.03		314		
	non noble metal	tin	7440-31-5	0.095	0.03		251		
	non noble metal	lead	7439-92-1	4.552	1.20	1.26	11988	12553	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50508	50574	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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